QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

APRIL 1985 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

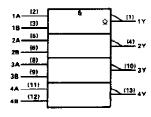
These devices contain four independent 2-input NAND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher VOH levels.

The SN5401 and SN54LS01 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7401 and SN74LS01 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	н	L
L	X	Н
×	L	н

logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

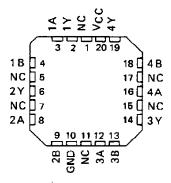
SN5401 . . . J PACKAGE SN54LS01 . . . J OR W PACKAGE SN7401 . . . N PACKAGE SN74LS01 . . . D OR N PACKAGE (TOP VIEW)

1Y	Пī	U14 Vcc
1A	\square 2	13 4 Y
1B	□3	12 🗆 4 B
2Y	□4	11 AA
2A	₫5	10 3Y
2B	□6	9∐ 3B
GND	□ 7	8 ∐ 3A

SN5401 . . , W PACKAGE (TOP VIEW)

	_	
1 A	ים	U 14] 4Y
1 B	\square^2	13 🕽 4 B
1 Y	₫3	12 AA
V c c	□4	סאם [ויו GND
2 Y	□5	10 Д 3 В
2A	4 6	9∐ 3A
2 B	口7	8 🗖 3 Ƴ

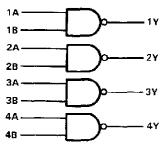
SN54LS01 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

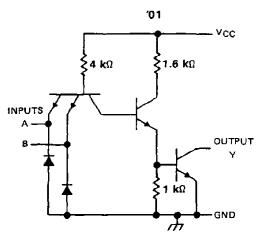
QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

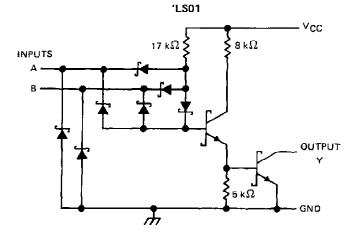
logic diagram (positive logic)



positive logic; $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1): '0)1, 'LS()1	 	 		 <i>.</i>	 			7	V
Input voltage: '01											
'LSO1			 	 		 	 			7	V
Off-state output voltage			 	 		 	 		. . .	7	٧
Operating free-air temperature range:	SN54'		 	 		 	 ~	55°	C to	125	°C
	SN74'		 	 		 	 	. 0	°C to	o 70	°C
Storage temperature range	<i>.</i>		 	 	.	 	 _	65°	C to	150	٥C

NOTE 1: Voltage values are with respect to network ground terminals.

SN5401, SN7401 QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

recommended operating conditions

		SN5401			UNIT		
	MIN	NOM	MAX	MIN	NOM	мах	UNIT
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
V _{IH} High-level input voltage	2		-	2			٧
VIL Low-level input voltage			0.8			0.8	V
VOH High-level output voltage			5.5			5.5	V
IOL Low-level output current			16			16	mA
TA Operating free-air temperature	- 55		125	0	·	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS [†]	SN5401	SN7401	UNIT
PARAMETER	TEST CONDITIONS.	MIN TYP# MAX	MIN TYP‡ MAX	UNIT
Vik	V _{CC} = MIN, _I = -12 mA	- 1.5	-1.5	V
	VCC = MIN, VIL = 0.8 V, VOH = 5.5 V		0.25	- ^
Іон	VCC = MIN, VIL = 0.7 V, VOH = 5.5 V	0.25		mA
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA	0.2 0.4	0.2 0.4	V
lj .	VCC = MAX, VI = 5.5 V	1	1	mΑ
lH.	$V_{CC} = MAX$, $V_{I} = 2.4 \text{ V}$	40	40	μΑ
ΊL	V _{CC} = MAX, V _I = 0.4 V	-1.6	-1.6	mA
І ссн	$V_{CC} = MAX, V_I = 0$	4 8	4 8	mA
¹ CCL	$V_{CC} = MAX$, $V_{\parallel} = 4.5 \text{ V}$	12 22	12 22	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	T O (OUTPUT)	TEST COND	MIN TY	P MAX	TINU	
[₹] PLH	A or B	٧	RL=4kΩ,	C _L = 15 pF	;	35 55	ns
^t PHL		,	R _L = 400 Ω,	C _L = 15 pF		8 15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_{A} = 25 °C.

SN54LS01, SN74LS01 QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

recommended operating conditions

		SN54LS01			UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4,5	5	5.5	4.75	5	5.25	٧
V _{IH} High-level input voltage	2			2			V
VIL Low-level input voltage		-	0.7			0.8	V
VOH High-level output voltage			5.5			5.5	V
IOL Low-level output current			4			8	mА
TA Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

040445750	ţ	TEST CONDITIONS †				01	ļ .			
PARAMETER	į	IEST CONDI	TIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
Vik	V _{CC} - MIN,	I _I = ~ 18 mA				- 1.5			- 1.5	V
•он	V _{CC} = MIN,	VIL = MAX,	V _{OH} = 5.5 ∨			0.1			0.1	mA
14	VCC = MIN,	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V,	IOL - 8 mA					0.35	0.5	
41	VCC = MAX.	V ₁ = 7 V				0.1			0.1	mA
ЙH	V _{CC} = MAX,	V ₁ = 2.7 V			_	20			20	μА
412	V _{CC} = MAX,	V ₁ = 0.4 V	· · · · · · · · · · · · · · · · · · ·			- 0.4			- 0.4	mA
1ссн	VCC = MAX,	V _I = 0			0.8	1.6		0.8	1.6	mΑ
1CCL	V _{CC} = MAX,	V ₁ = 4.5 V			2.4	4.4		2.4	4.4	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	MIN	TYP	MAX	UNIT	
tPLH .	A or B	·	R ₁ = 2 kΩ,	C _L = 15 pF		17	32	ns
[‡] PHL	70.0		11[- 2 K32,	C[13bi		15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	Samples Not Available
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	Samples Not Available
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	Samples Not Available
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.





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OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN5401, SN54LS01, SN7401, SN74LS01:

Catalog: SN7401, SN74LS01

Military: SN5401, SN54LS01

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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